

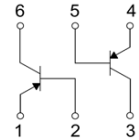
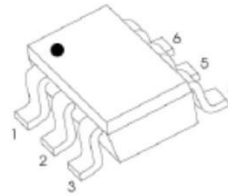
## Features

- Complementary to MMDT5551DW
- Small Surface Mount Package
- Ideal for Medium Power Amplification and Switching

K4N

SOT-363

Equivalent Circuit



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

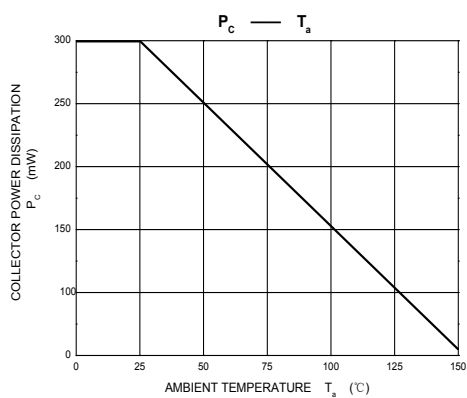
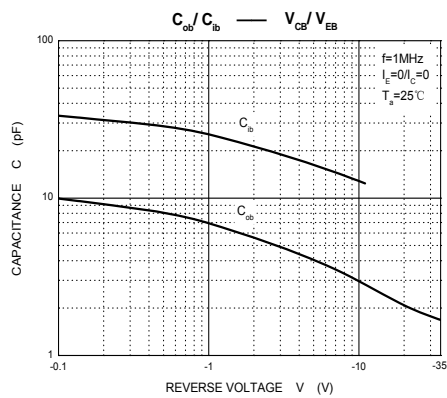
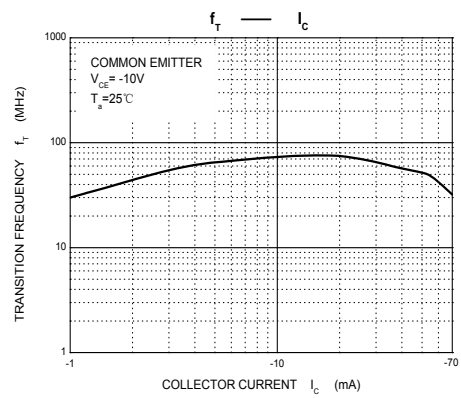
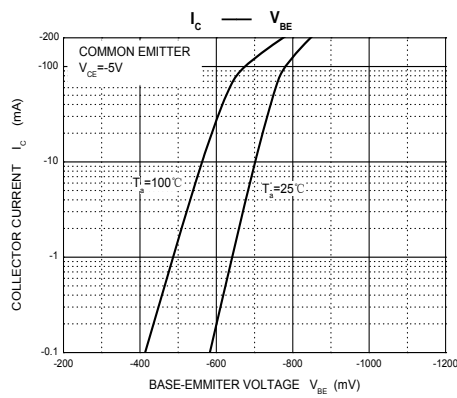
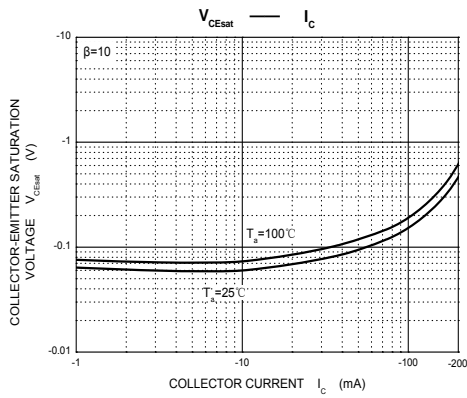
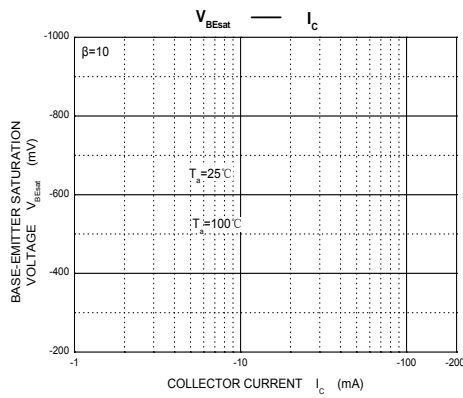
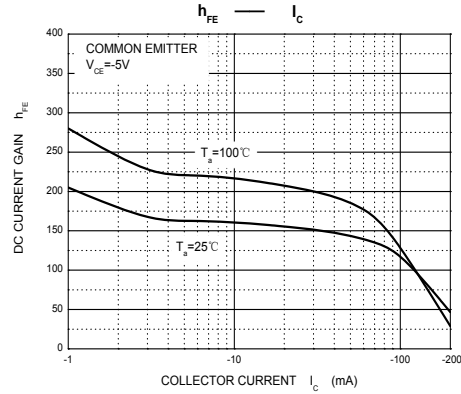
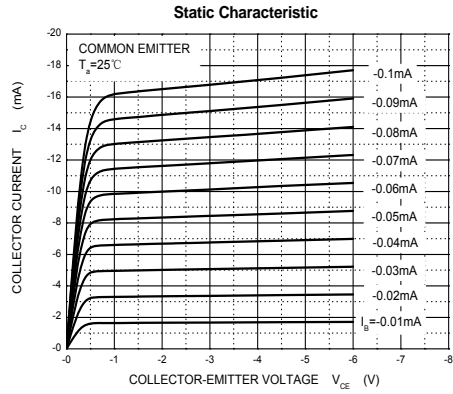
MAXIMUM RATINGS TR1 ( $T_a=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{CBO}$	Collector-Base Voltage	-160	V
$V_{CEO}$	Collector-Emitter Voltage	-150	V
$V_{EBO}$	Emitter-Base Voltage	-5	V
$I_C$	Collector Current	-600	mA
$P_C$	Collector Power Dissipation	300	mW
$R_{\theta JA}$	Thermal Resistance From Junction To Ambient	625	$^{\circ}\text{C}/\text{W}$
$T_j$	Junction Temperature	150	$^{\circ}\text{C}$
$T_{stg}$	Storage Temperature	-55~+150	$^{\circ}\text{C}$

## Electrical Characteristics ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	$V_{(BR)CBO}$	$I_C=-100\mu\text{A}, I_E=0$	-160			V
Collector-emitter breakdown voltage	$V_{(BR)CEO}$	$I_C=-1\text{mA}, I_B=0$	-150			V
Emitter-base breakdown voltage	$V_{(BR)EBO}$	$I_E=-10\mu\text{A}, I_C=0$	-5			V
Collector cut-off current	$I_{CBO}$	$V_{CB}=-120\text{V}, I_E=0$			-50	nA
Emitter cut-off current	$I_{EBO}$	$V_{EB}=-3\text{V}, I_C=0$			-50	nA
DC current gain	$h_{FE}$	$V_{CE}=-5\text{V}, I_C=-1\text{mA}$	50			
		$V_{CE}=-5\text{V}, I_C=-10\text{mA}$	60		300	
		$V_{CE}=-5\text{V}, I_C=-50\text{mA}$	50			
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C=-50\text{mA}, I_B=-5\text{mA}$			-0.5	V
		$I_C=-10\text{mA}, I_B=-1\text{mA}$			-0.2	V
Base-emitter saturation voltage	$V_{BE(sat)}$	$I_C=-50\text{mA}, I_B=-5\text{mA}$			-1	V
		$I_C=-10\text{mA}, I_B=-1\text{mA}$			-1	V
Transition frequency	$f_T$	$V_{CE}=-10\text{V}, I_C=-10\text{mA}, f=100\text{MHz}$	100			MHz
Collector output capacitance	$C_{ob}$	$V_{CB}=-10\text{V}, I_E=0, f=1\text{MHz}$			6	pF

RATING AND CHARACTERISTIC CURVES



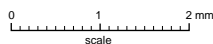
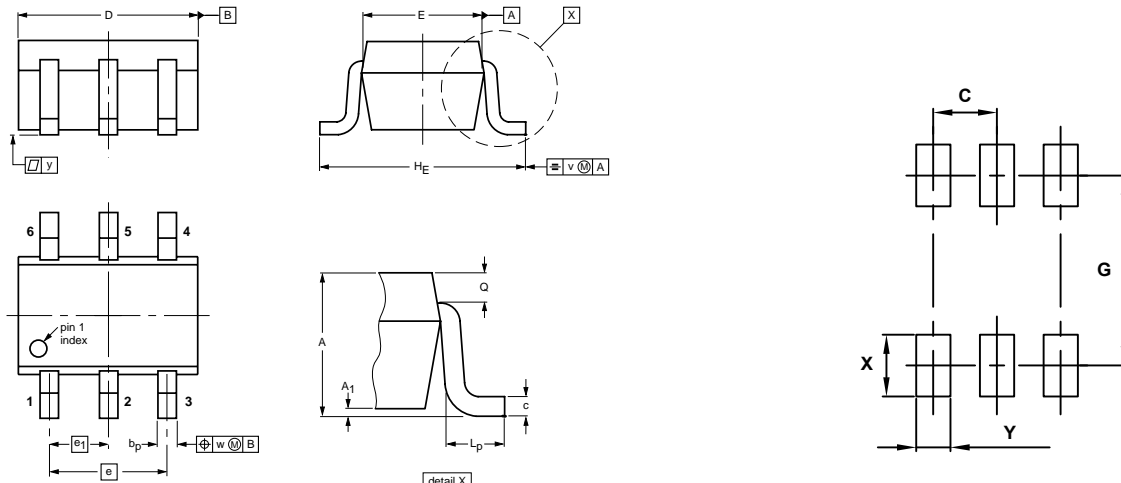
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150 °C
	-Temperature Max( $T_{s(max)}$ )	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3 °C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217 °C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout

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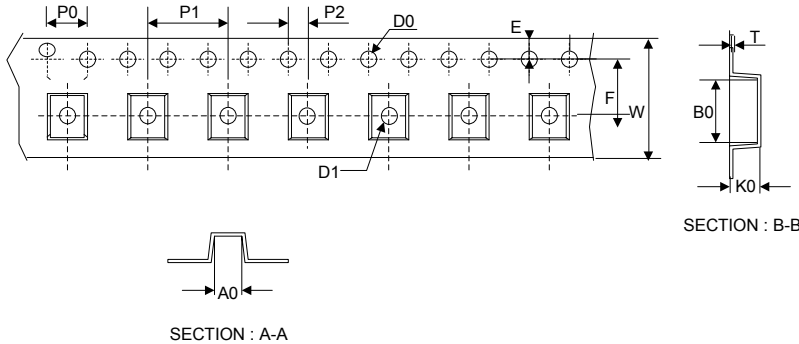
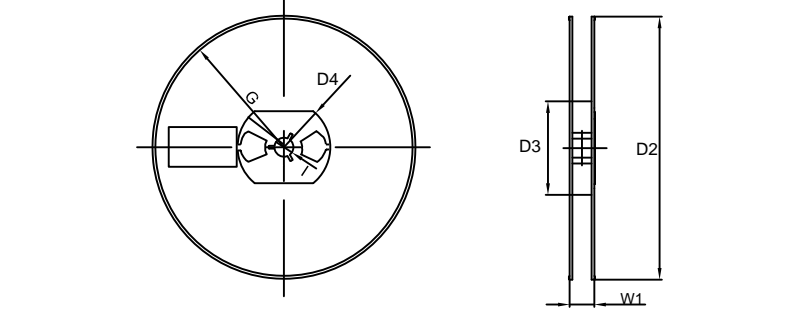


Dimensions	Value (in mm)
C	0.65
G	1.90
X	0.85
Y	0.40

DIMENSIONS (mm are the original dimensions)

UNIT	A	A1 max	bp	c	D	E	e	e1	HE	Lp	Q	v	w	y
mm	1.1 0.8	0.1	0.30 0.20	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.25 0.15	0.2	0.2	0.1

Tape & reel specification

Tape	Symbol	Dimension (mm)	
	P0	4.00±0.20	
	P1	4.00±0.20	
	P2	2.00±0.20	
	D0	1.55±0.20	
	D1	1.00±0.20	
	E	1.55±0.25	
	F	3.60±0.20	
	W	8.00±0.20	
	A0	3.00±0.20	
	B0	3.00±0.20	
	K0	1.30±0.20	
	T	0.20±0.20	
	7" Reel	D2	177.0±5.0
		D3	55Min.
		D4	R24.6±2.0
G		R82.0±2.0	
I		13.0±2.0	
W1		10.20±3.0	
Quantity: 3000PCS			